

Day 1 - Tuesday 17th November 2020

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows, Conference Chair

Satisfying demand for more data

Sponsored by JTA/Takatori

PANEL SESSION

09:00 Enabling wider mobile bandwidth no matter what frequency you choose.

Presented by Ben Thomas - Qorvo

PANEL SESSION

09:25 Assessing the impact of 5G front-ends on the world' leading GaAs fabs

Presented by Eric Higham - Strategy Analytics

PANEL SESSION

09:45 Millimetre-wave MMICs and integrated solutions enabling high-throughput 5G deployments

Presented by Eric Leclerc - United Monolithic Semiconductors

PANEL SESSION

10:05 The future of Germanium: Breakthrough Opportunities

Presented by Pieter Arickx - Umicore

PANEL SESSION

10:25 Improving yield for 5G market through defect inspection and metrology

Presented by Varun Gupta - KLA Corporation

PANEL SESSION

10:45 5G's impact on RF Front-End: from Telecom Infrastructure to Handsets

Presented by Claire Troadec - Yole Développement

11:05 Morning Break - Sponsored by Hewlett Packard Enterprise

Seeking new opportunities for LEDs and lasers

Sponsored by Inspectrology

PANEL SESSION

11:35 Improving the architecture of the GaN VCSEL

Presented by Tatsushi Hamaguchi - Sony Corp.

PANEL SESSION

12:00 Can MicroLEDs and VCSELs revolutionize the Solid State Lighting Industry?

Presented by Pars Mukish - Yole Development

PANEL SESSION

12:20 Refining microLED technology

Presented by Wei Sin Tan - Plessey Semiconductors

12:40 Lunch Break - Sponsored by Hewlett Packard Enterprise

PANEL SESSION

13:55 Advanced technology of plasma dicing for GaAs VCSEL

Presented by Akihiro Itou - Panasonic

PANEL SESSION

14:15 Optimizing 200mm Metal Lift-off for Smaller Dimensions

Presented by Philip Greene - Ferrotec

PANEL SESSION

14:35 Recent trends in LED and LASER diode device material characterization

Presented by Yves Lacroix - YSystems Ltd

14:55 Afternoon Break - Sponsored by Hewlett Packard Enterprise

PANEL SESSION

15:25 Highly uniform films and tool stability - key drivers for Micro LED production

Presented by Stefan Seifried - Evatec

PANEL SESSION

15:45 Presentation Title to be Confirmed

PANEL SESSION

16:05 Seeking new opportunities for LEDs and lasers

Presented by Samuel Sonderegger - Attolight

PANEL SESSION

16:25 Leading-Edge MOCVD Technology Enabling Next-Generation Photonics Applications

Presented by Mark McKee - Veeco

PANEL SESSION

16:45 Compound Semiconductor Integration – Wafer Bonding towards new Di(e)nsions

Presented by Thomas Uhrmann - EV Group

17:05 Closing Remarks

17:10 Networking Drinks Reception and Dinner

Day 2 - Wednesday 18th November 2020

08:00 Registration and welcome refreshments

08:50 Housekeeping by Chris Meadows, Conference Chair

Ramping volumes in the power electronics sector

Sponsored by ClassOne Technology

PANEL SESSION

09:00 Driving the revolution in wide bandgap devices
Presented by John Palmour - Wolfspeed

PANEL SESSION

09:25 The SiC & GaN Power Semiconductor Market: Forecasts and Drivers
Presented by Richard Eden - IHS Markit

PANEL SESSION

09:45 Driving the adoption of CoolGaN technology
Presented by Gerald Deboy - Infineon

PANEL SESSION

10:05 Solutions for high volume manufacturing of wide bandgap materials
Presented by Jens Voigt - AIXTRON

PANEL SESSION

10:25 Expanding opportunities for 650 V GaN FETs
Presented by Frédéric Dupont - Exagan

PANEL SESSION

10:45 Latest technologies for laser dicing, blade dicing of SiC and new ultra-thin grinding
Presented by Gerald Klug - DISCO HI-TEC EUROPE GmbH

PANEL SESSION

11:05 Reinforcement Factories
Presented by Julie Orlando - Nanotronics

11:25 Morning Break - Sponsored by Hewlett Packard Enterprise

PANEL SESSION

11:55 Using high speed XRF to improve and monitor SiC substrate quality
Presented by Paul Ryan - Bruker

PANEL SESSION

12:15 Advanced in-situ metrology for high-yield epitaxy of SiC/SiC, GaN/SiC and GaN/Si device structures
Presented by Iris Claussen - Laytec

PANEL SESSION

12:35 Presentation Title to be Confirmed - Revasum
Presented by Rob Rhoades - Revasum

PANEL SESSION

12:55 200mm GaN Power: Technology and Commercialization Status on Scalable QST® Platform
Presented by Vlad Odnoblyudov - QROMIS

PANEL SESSION

13:15 Advanced Plasma Processing solutions enabling the cost down per wafer and critical device performance required to accelerate the HVM of GaN and SiC Power devices.
Presented by Frazer Anderson - Oxford Instruments

13:35 Lunch Break - Sponsored by Hewlett Packard enterprise

Taking wide bandgap devices to their ultimate limits

Sponsored by Precision Fabricators

PANEL SESSION

14:50 Ramping production of gallium oxide diodes and transistors
Presented by Takashi Shinohe - FLOSFIA

PANEL SESSION

15:15 A New Technology of Commercialization for GaN on Diamond HEMTs
Presented by Won Sang Lee - RFHIC US Corp

PANEL SESSION

15:35 Presentation Title to be Confirmed - EpiGaN
Presented by Marianne Germain - EpiGaN

Enhancing the automobile

Sponsored by ClassOne Technology

PANEL SESSION

15:55 **High-power blue VCSELS and VCSEL arrays**
Presented by Masaru Kuramoto - Stanley Electric

PANEL SESSION

16:20 **Compound semiconductor adoption by automotive market**
Presented by Ezgi Dogmus - Yole Développement

PANEL SESSION

16:40 **Electrochemical Deposition of Gold as Optimal Choice for Device Cost and Performance**
Presented by John Ghekiere - ClassOne

PANEL SESSION

17:00 **New CS Markets Challenge Traditional Reliability Testing Paradigms**
Presented by Roland Shaw - Accel RF

PANEL SESSION

17:20 **SiC: From Niche to Mass Production**
Presented by Aly Mashaly - Rohm Semiconductor

PANEL SESSION

17:40 **Speeding On-board Charging with Automotive-qualified GaN FETs**
Presented by Philip Zuk - Transphorm

18:00 **Closing Remarks**

